

PATENT APPLICATION SERIAL NO. _____

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
FEE RECORD SHEET

05/21/2001 AZERGAM1 00000009 09858238

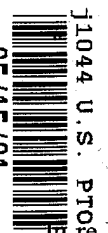
01 FC:101	710.00 OP
02 FC:102	320.00 OP
03 FC:103	270.00 OP

PTO-1556
(5/87)

*U.S. GPO: 2000-468-987/39595

5-17-01

05/15/01



Jc997 U.S. PTO
09/858238

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Tee Onn Chong et al.
Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

Attorney Docket No.: 884.419US1

PATENT APPLICATION TRANSMITTAL

BOX PATENT APPLICATION

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ Utility Patent Application under 37 CFR § 1.53(b) comprising:
 - ☒ Specification (27 pgs, including claims numbered 1 through 35 and a 1 page Abstract).
 - ☒ Formal Drawing(s) (12 sheets).
 - ☒ Signed Combined Declaration and Power of Attorney (8 pgs).
 - ☒ Check in the amount of \$1,300.00 to pay the filing fee.
- ☒ Assignment of the invention to Intel Corporation (4 pgs) and Recordation Form Cover Sheet.
- ☒ Check in the amount of \$40.00 to pay the Assignment recording fee.

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	35 - 20 =	15	x 18 =	\$270.00
INDEPENDENT CLAIMS	7 - 3 =	4	x 80 =	\$320.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$710.00
TOTAL				\$1,300.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date of Deposit: May 15, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.